

LOCTITE
BERGQUIST

BERGQUIST® GAP FILLER TGF 10000

2-part gap filler with high thermal conductivity for electronics components



CUSTOMER NEEDS

- **High thermal conductivity material** (up to 10W/m·K) for **heat dissipation** in high-power ADAS SoC module
- **Reliable in harsh conditions:** humidity, thermal shock (-40 – 150°C), heat aging (150°C), vibration
- **Easy dispensing**, no equipment blocking



HENKEL SOLUTIONS

- Low volatile, silicone based thermally conductive liquid gap filler with **high thermal rating 10W/m·k**
- **<20% thermal impedance** increase after 1000h, **excellent gap stability**
- **Optimized viscosity/filler** for **high dispense rate, robust mixing; no blocking** after 2hr air pressure
- Reduced D4 to D10 content **ensures compliance** and **minimizes outgassing**.
- Faster dispensing property **increases throughput** and **saves energy**.

CONTACT US TO LEARN MORE

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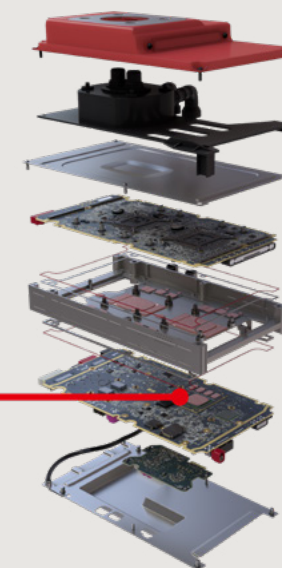
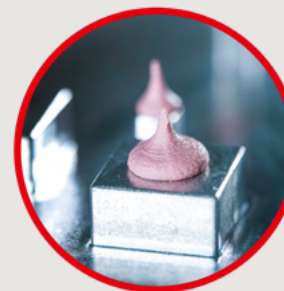
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Henkel

Henkel Adhesive Technologies



ADAS SoC module



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